

TITLE OF THE INVENTION: METHOD FOR GRINDING A WAFER

Abstract

A method for grinding a wafer is provided. The method comprises: providing a wafer having a back side and a front side opposite to the back side, wherein the wafer further comprises a central zone for accommodating semiconductor units and a peripheral zone surrounding the central zone; forming a trench within the peripheral zone and extending along substantially an entire circumference of the peripheral zone, wherein the trench is exposed from the front side of the wafer; filling the trench with a filler to form a spacer ring within the peripheral zone, wherein the spacer ring isolates the central zone from an edge of the wafer; attaching the wafer onto a platform at the front side of the wafer; and grinding the wafer from the back side of the wafer.

[FIG. 1F]